

Using the TPS650061EVM 2.25 MHz Step-Down Converter with Dual LDO

The TPS650061 is a single chip Power Management ICs for portable applications. The device combines a single step-down converter with two low dropout regulators and a Supply Voltage Supervisor (SVS). The step-down converter enters a low power mode at light load for maximum efficiency across the widest possible range of load currents. For low noise applications the device can be forced into fixed frequency PWM mode. The step-down converter allows the use of a small inductor and capacitors to achieve a small solution size. The step-down converter has Power Good status output that can be used for sequencing. The LDOs are capable of supplying 300mA and can operate with an input voltage range between 1.6V and 6.0V, allowing them to be supplied from the step-down converter or directly from the main battery.

The step-down converter and the LDOs have separate voltage inputs and enables, allowing for design and sequencing flexibility.

Contents

1	Introduction	2
1.1	Applications	2
1.2	Features	2
2	TPS650061 EVM Electrical Performance Specifications	3
3	Schematic	4
4	Connector and Test Point Description	5
4.1	J1 – VIN/GND	5
4.2	J2 – RST/GND	5
4.3	J3 – VODC / GND	5
4.4	J4– VLDO1/GND	5
4.5	J5 – VLDO2	5
4.6	J6 – PG/GND	5
4.7	JP1 – VINLDO1	5
4.8	JP2 – VINLDO2	5
4.9	JP3 –ENDCDC	6
4.10	JP4 –ENLDO1	6
4.11	JP5 – ENLDO2	6
4.12	JP6 –MODE	6
4.13	JP7 – MRPU	6
4.14	JP8 – VPU	6
4.15	JP9 – RSTSNS_IN	6
5	TPS650061 Typical Performance Data and Characteristic Curves	6
5.1	Efficiency	7
5.2	Line and Load Regulation	7
5.3	Output Voltage Ripple	9
5.4	Startup Timing	10
6	EVM Assembly Drawings and Layout	11
7	List of Materials	14

List of Figures

1	TPS650061EVM Schematic	4
2	TPS650061 Efficiency vs Load Current.....	7

3	TPS650061 DCDC Converter Load Transient Response	7
4	TPS650061 LDOx Load Transient Response.....	8
5	TPS650061 DCDC Converter Line Transient Response	8
6	TPS650061 LDOx Line Transient Response.....	9
7	TPS650061 Output Voltage Ripple (MODE = low)	9
8	TPS650061 Output Voltage Ripple (MODE = high)	10
9	TPS650061 DCDC Converter Startup Timing	10
10	TPS650061EVM Component Placement (Viewed from Top)	11
11	TPS650061EVM Top Copper (Viewed from Top).....	12
12	TPS650061EVM Bottom Copper (View from Bottom)	13

List of Tables

1	TPS650061EVM Electrical and Performance Specifications.....	3
2	TPS650061EVM Bill of Materials.....	14

1 Introduction

1.1 Applications

- Point of Load
- Embedded Processor Power
- Cell Phones, Smart-phones
- PDAs, Pocket PCs
- Portable Media Players

1.2 Features

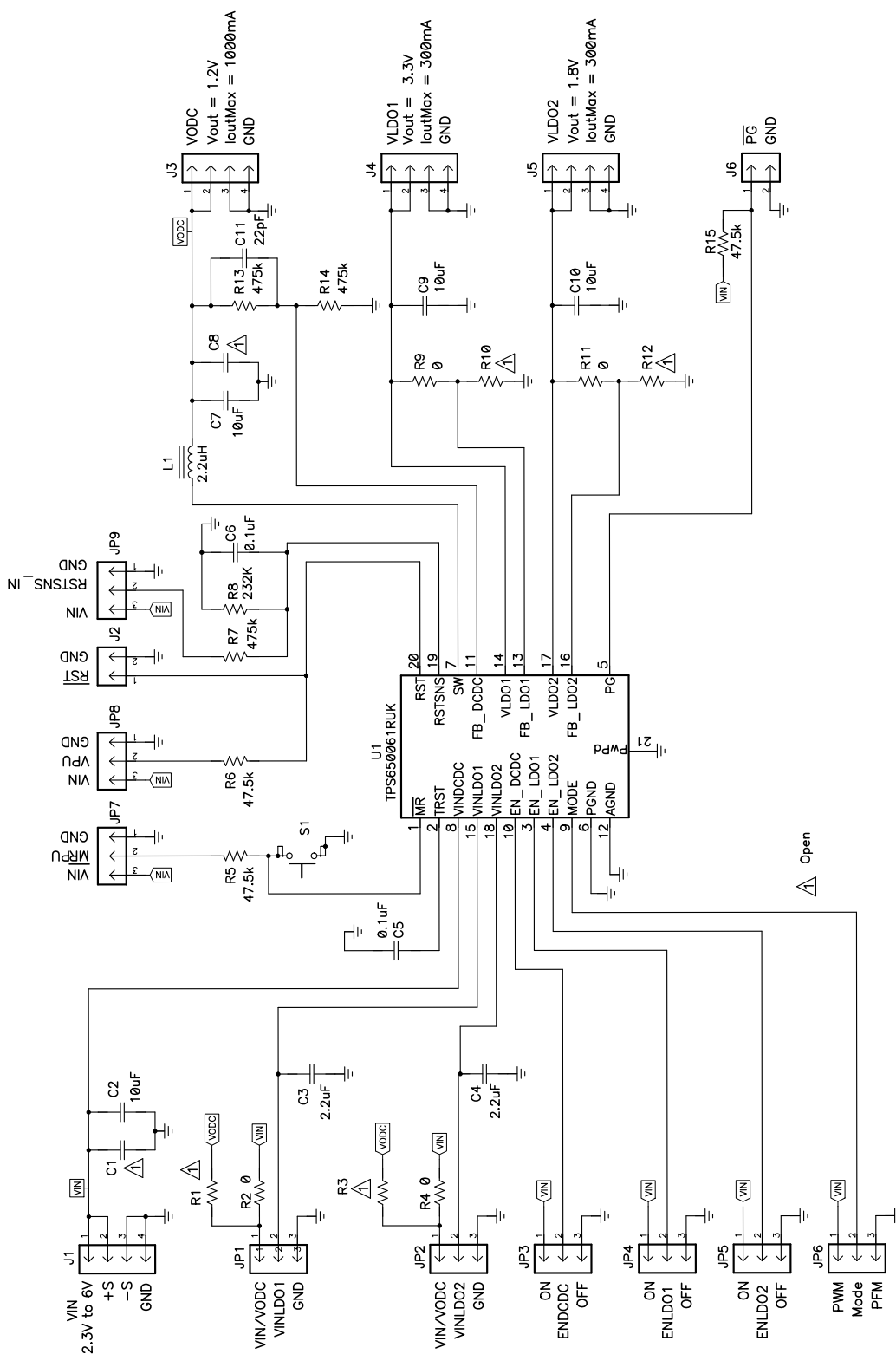
- Input Voltage Rating : 2.3-V up to 6.0-V
- Output voltages of DCDC converter externally adjustable, output voltages of LDOs internally fixed
- Output Current Rating 1.0 A (DCDC converter) / 300-mA (LDOs)
- Spread Spectrum Clock (SSC) for best EMI performance
- Supply Voltage Supervisor : Adjustable Reset Voltage / Time , Manual Reset
- 2.25-MHz Switching Frequency
- 20 pin 3mm x 3mm QFN package

2 TPS650061 EVM Electrical Performance Specifications

Table 1. TPS650061EVM Electrical and Performance Specifications

PARAMETER		NOTES AND CONDITIONS	MIN	NOM	MAX	UNITS
INPUT CHARACTERISTICS						
V_{IN}	Input Voltage		2.3		6.0	V
V_{IN_UVLO}	Input UVLO	VIN falling	1.72	1.77	1.82	V
Hysteresis				160		
OUTPUT CHARACTERISTICS						
V_{ODC}	Output Voltage DCDC	$V_{IN} = \text{Nom}$, $I_{OUT} = \text{Nom}$		1.2		V
	Accuracy DCDC1	VINDCDC 2.3V to 6V, With 1% tolerance resistors	PFM/PWM		-3.5%	3.5%
			PWM		3%	
I_{OUTDC}	Output Current DCDC	$V_{INDCDC} = 2.3 \text{ V to } 2.5 \text{ V}$			300	mA
		$V_{INDCDC} = 2.7 \text{ V to } 6 \text{ V}$		1000	600	
VLDO1	Output Voltage LDO1	$V_{IN} = \text{Nom}$, $I_{OUT} = \text{Nom}$		3.3		V
$I_{OUTLDO1}$	Output Current LDO1	Continuous output current			300	mA
VLDO2	Output Voltage LDO2			1.8		V
$I_{OUTLDO2}$	Output Current LDO2	Continuous output current			300	mA
	Accuracy LDOs	VINLDO = 1.6 V to 6 V, Iout = 1 mA to 175 mA, VLDOx = 1.2 V, With 1% tolerance resistors	-5.5%		5.5%	
		VINLDO = 1.5 V to 6 V, Iout = 1 mA to 300 mA, VLDOx = 1.2 V, With 1% tolerance resistors	-5.5%		5.5%	
	Supply Voltage Supervisor					
	RST Trip Voltage	R7 = 475k, R8 = 232k, JP9 connected between VIN and RSTSN_IN		1.8		V
t_{RST}	RST Recovery Time	C5 = 0.1 μF		30		ms
SYSTEMS CHARACTERISTICS						
F_{SW}	Switching Frequency		1722	2250	2847	kHz

3 Schematic



For Reference Only, See Table 4: Bill of Materials for Specific Values

Figure 1. TPS650061EVM Schematic

4 Connector and Test Point Description

4.1 J1 – VIN/GND

The input power supply has to be connected to this header. The power supply must be connected between J1 pins 1 and 2 (positive connection) and J1 pins 3 and 4 (GND). The leads to the input supply should be twisted and kept as short as possible. The input voltage has to be between 2.3-V and 6-V.

4.2 J2 – \overline{RST} /GND

J2 pin 1 is connected to the open drain output \overline{RST} of the Supply Voltage Supervisor.

\overline{RST} is pulled low if either manual reset input \overline{MR} is low or the voltage on RSTSNS is below the threshold.

If manual reset \overline{MR} is released or the voltage on RSTSNS rises above the threshold voltage \overline{RST} goes high again after the reset recovery time t_{RST} exceeded.

4.3 J3 – VODC / GND

This header is the output of the step-down converter. This output voltage is externally adjustable for the TPS650061. The default setting on the EVM is 1.2V. VODC is capable of sourcing up to 1.0-A. A load can be connected between J3 pins 1 and 2 (positive connection) and J3 pins 3 and 4 (GND).

4.4 J4– VLDO1/GND

This header is the output of LDO1. This output voltage is internally fixed for the TPS650061 at 3.3-V. VLDO2 is capable of sourcing up to 300-mA. A load can be connected between J4 pins 1 and 2 (positive connection) and J4 pins 3 and 4 (GND).

4.5 J5 – VLDO2

This header is the output of LDO2. This output voltage is internally fixed for the TPS650061 at 1.8-V. VLDO2 is capable of sourcing up to 300-mA. A load can be connected between J5 pins 1 and 2 (positive connection) and J5 pins 3 and 4 (GND).

4.6 J6 – PG/GND

J6 pin 1 is pulled to GND if the output voltages of the DCDC converter and both LDOs are > 90% of their set point and all enable pins are pulled high.

J6 pin 1 is pulled up to the selected pull-up voltage level if any of the output voltages VODC, VLDO1 or VLDO2 is < 90% of its set point or all enable pins are pulled low.

4.7 JP1 – VINLDO1

This header is the input supply for LDO1. Placing a shorting bar between VINLDO1 and VINDC/VODC supplies LDO1 from VIN with R2. It can be also supplied from the output of the converter VODC with R1 (not assembled). An external power supply can be connected between JP1 pin 2 (VINLDO1) and pin 3 (GND). Note that the resistors R1 and R2 should be removed when supplying the LDO from an external power supply.

4.8 JP2 – VINLDO2

This header is the input supply for LDO2. Placing a shorting bar between VINLDO2 and VINDC/VODC supplies LDO2 from VIN with R4. It can be also supplied from the output of the converter VODC with R3 (not assembled). An external power supply can be connected between JP2 pin 2 (VINLDO2) and pin 3 (GND). Note that the resistors R3 and R4 should be removed when supplying the LDO from an external power supply.

4.9 JP3 – ENDCDC

Placing a shorting bar between ENDCDC and ON ties the EN pin of the DCDC converter to VIN, thereby enabling the DCDC converter. Placing a shorting bar between ENDCDC and OFF ties the EN pin of the DCDC converter to GND, thereby disabling the DCDC converter.

4.10 JP4 – ENLDO1

Placing a shorting bar between ENLDO1 and ON ties the EN pin of LDO1 to VIN, thereby enabling LDO1. Placing a shorting bar between ENLDO1 and OFF ties the EN pin of LDO1 to GND, thereby disabling LDO1.

4.11 JP5 – ENLDO2

Placing a shorting bar between ENLDO2 and ON ties the EN pin of LDO2 to VIN, thereby enabling LDO2. Placing a shorting bar between ENLDO2 and OFF ties the EN pin of LDO2 to GND, thereby disabling LDO2.

4.12 JP6 – MODE

JP6 selects the forced PWM or Power Save Mode (PSM) operation for the DCDC converter. Placing a shorting bar between MODE and PWM ties the MODE pin of TPS650061 to VIN, thereby selecting forced PWM operating mode for the DCDC converter. Placing a shorting bar between MODE and PFM ties the MODE pin of TPS650061 to GND, thereby selecting Power Save Mode operating mode for the DCDC converter at light-load conditions. If Power Save Mode is selected the DCDC converter will automatically switch to PWM mode at heavier load conditions.

4.13 JP7 – MRPU

JP7 selects the pull-up voltage for the Manual Reset input $\overline{\text{MRPU}}$ of the TPS650061. Placing a shorting bar between VIN and $\overline{\text{MRPU}}$ selects VIN as pull-up voltage. Any other voltage source can be used, by removing the shorting bar and connecting a power supply between $\overline{\text{MRPU}}$ (positive connection) and GND (negative connection). In the default setup VIN is used as pull-up voltage.

4.14 JP8 – VPU

JP8 selects the pull-up voltage used for the $\overline{\text{PG}}$ output.

Placing a shorting bar between VPU and VIN select VIN as pull-up voltage. Any other pull-up voltage can be used by removing the shorting bar and connecting a power supply between VPU and GND.

4.15 JP9 – RSTSNS_IN

JP9 selects the voltage rail that is monitored by the Supply Voltage Supervisor (SVS). Placing a shorting bar between VIN and RSTSNS_IN selects VIN as monitored rail. Any other voltage rail can be connected to the SVS input by removing the shorting bar and connecting the rail between RSTSNS_IN and GND.

In default setup VIN is monitored by the SVS.

5 TPS650061 Typical Performance Data and Characteristic Curves

Figure 2 through Figure 9 present typical performance curves for the TPS650061. Since actual performance data can be affected by measurement techniques and environmental variables, these curves are presented for reference and may differ from actual field measurements.

5.1 Efficiency

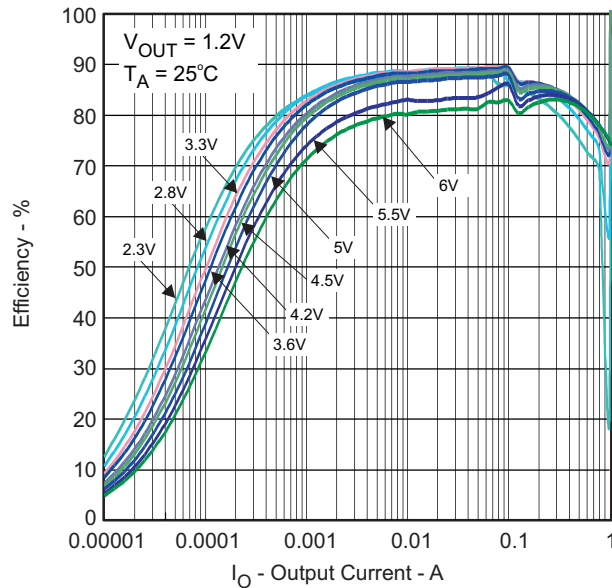


Figure 2. TPS650061 Efficiency vs Load Current

5.2 Line and Load Regulation

Figure 3 and Figure 4 show the load transient response of the DCDC converter and LDO, while Figure 5 and Figure 6 show the line transient response.

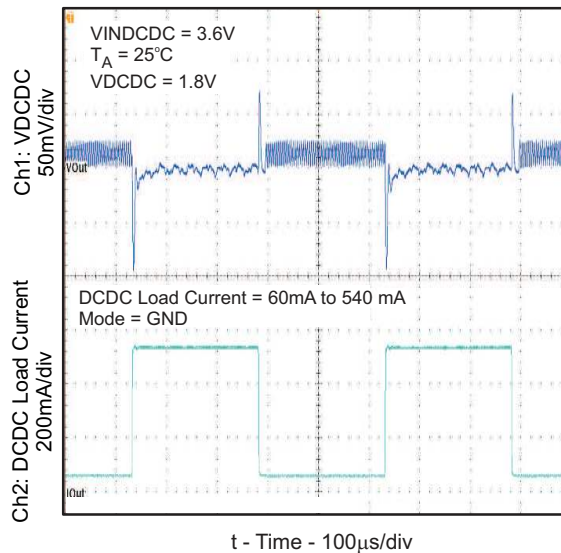
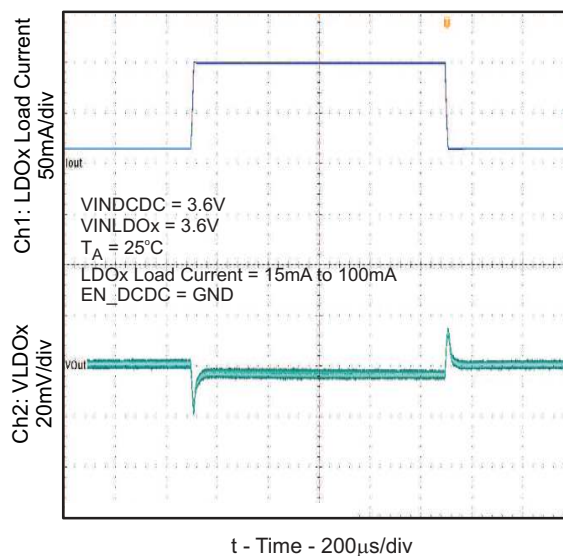
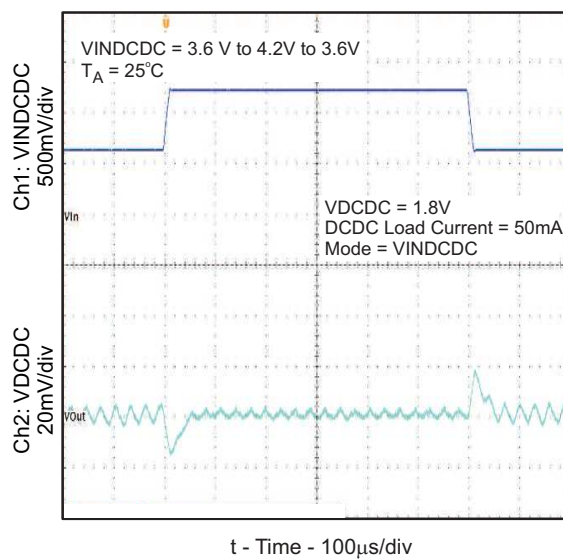


Figure 3. TPS650061 DCDC Converter Load Transient Response


Figure 4. TPS650061 LDOx Load Transient Response

Figure 5. TPS650061 DCDC Converter Line Transient Response

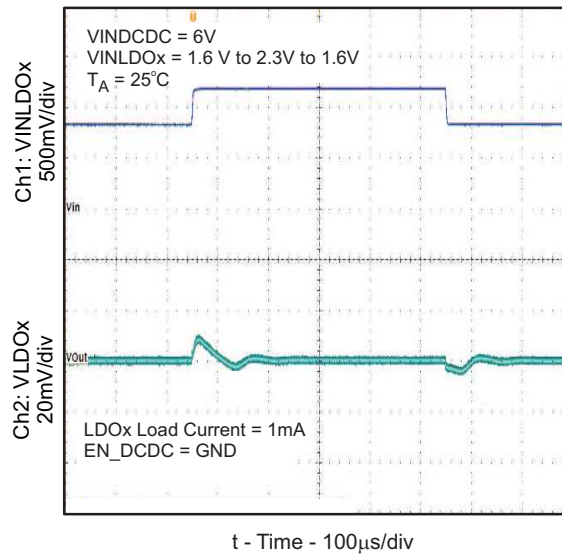


Figure 6. TPS650061 LDOx Line Transient Response

5.3 Output Voltage Ripple

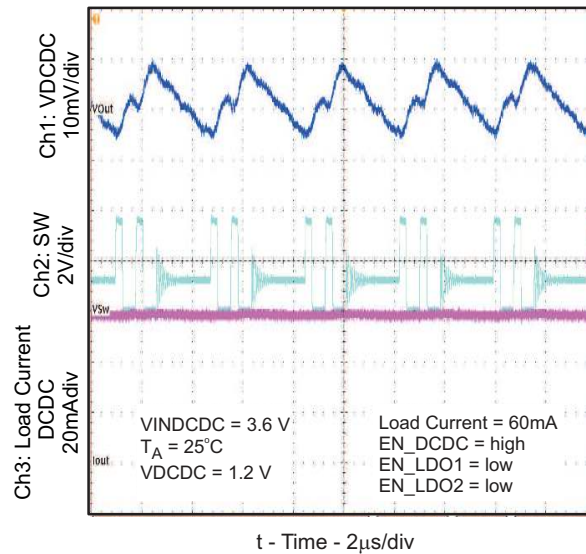
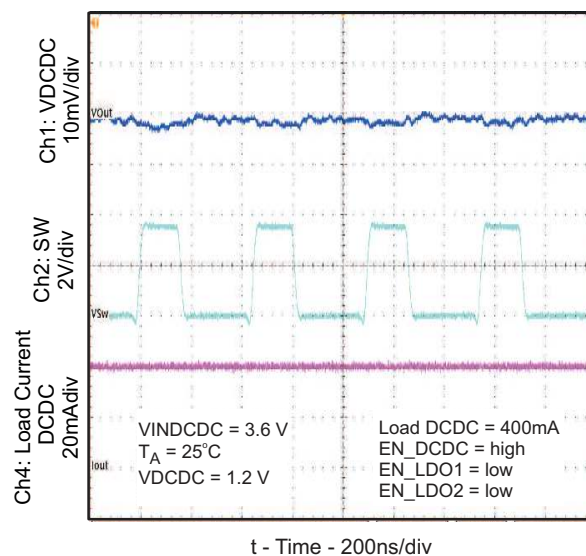
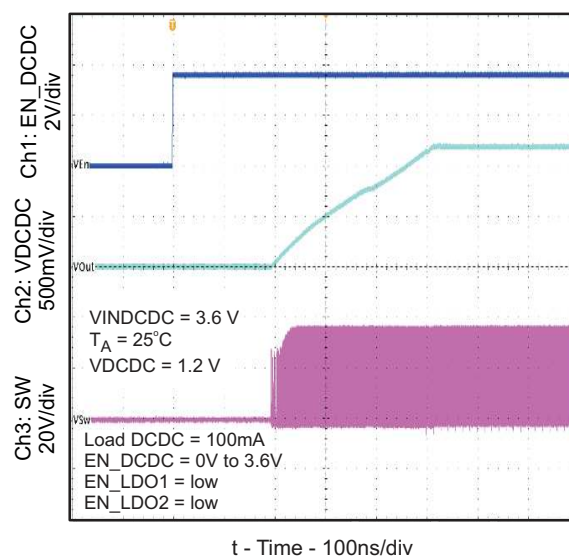


Figure 7. TPS650061 Output Voltage Ripple (MODE = low)


Figure 8. TPS650061 Output Voltage Ripple (MODE = high)

5.4 Startup Timing


Figure 9. TPS650061 DCDC Converter Startup Timing

6 EVM Assembly Drawings and Layout

The following figures (Figure 10 through Figure 12) show the design of the TPS650061EVM printed circuit board. The EVM has been designed using a 2-Layer, 1oz copper-clad circuit board 2.4" x 2.0" (61.09mm x 50.80mm).

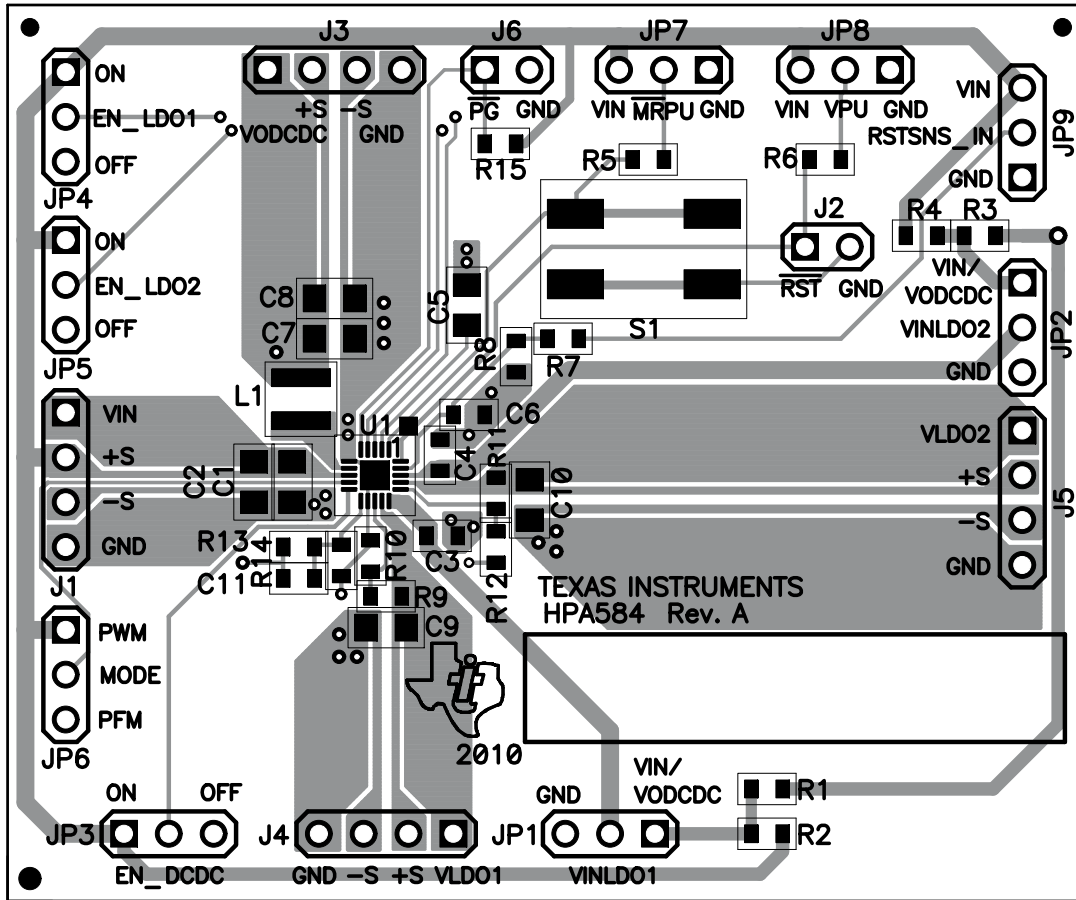


Figure 10. TPS650061EVM Component Placement (Viewed from Top)

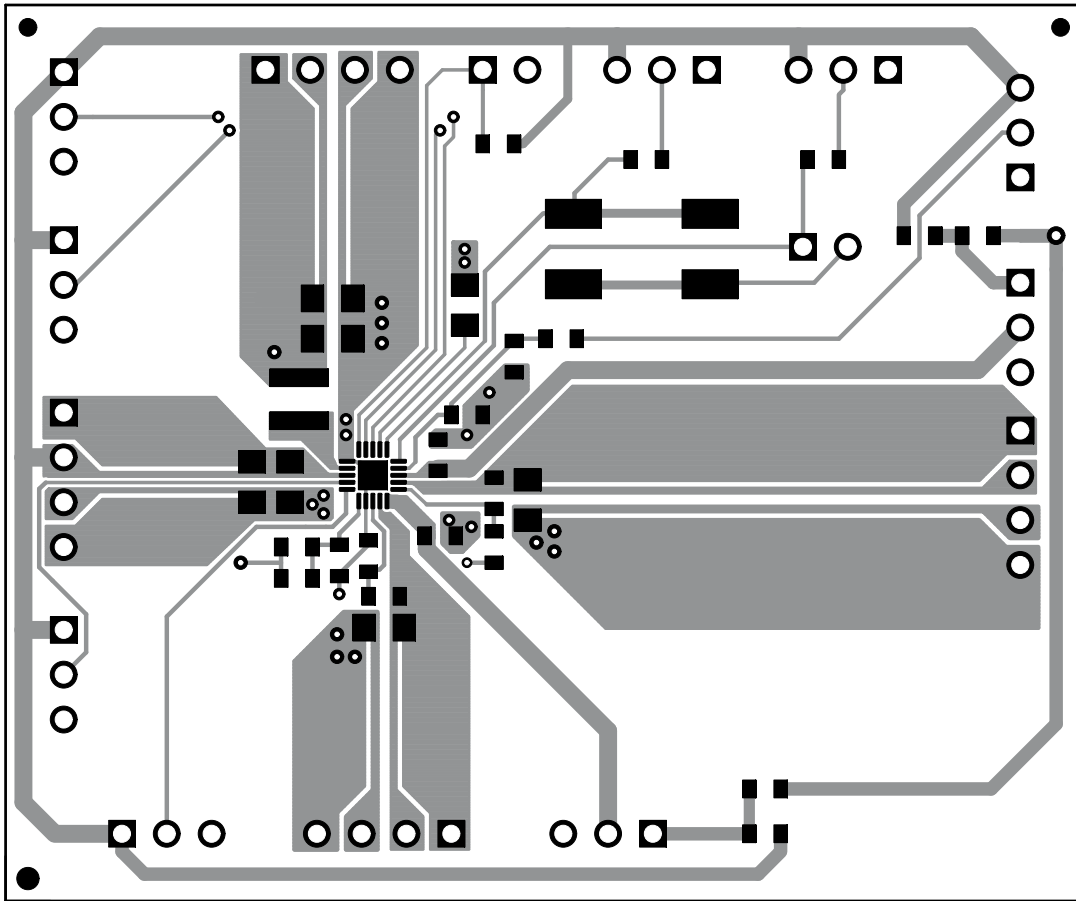


Figure 11. TPS650061EVM Top Copper (Viewed from Top)

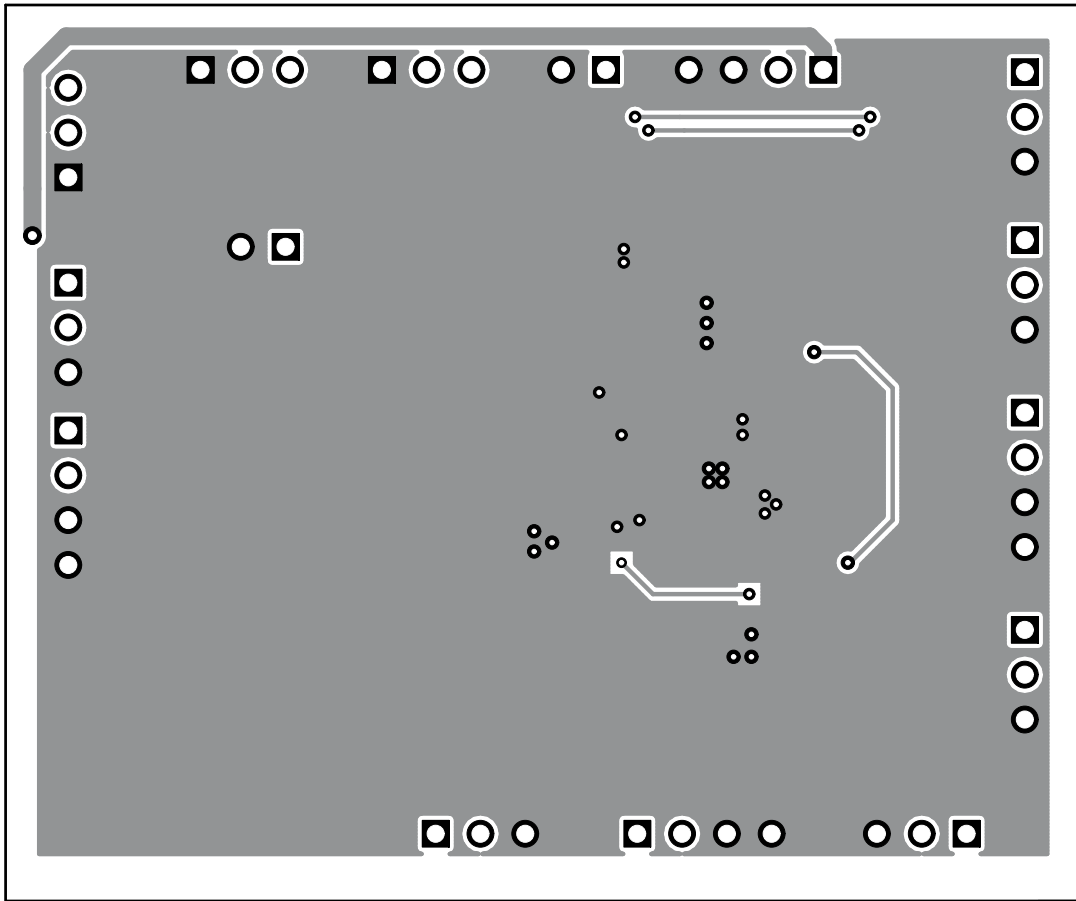


Figure 12. TPS650061EVM Bottom Copper (View from Bottom)

7 List of Materials

Table 2 lists the EVM components as configured according to the schematic shown in Figure 1.

Table 2. TPS650061EVM Bill of Materials

Count	RefDes	Value	Description	Size	Part Number	MFR
0	C1, C8	open	Capacitor, Ceramic, 10V, X5R, 10%,	0805	Std	Std
1	C11	22pF	Capacitor, Ceramic, 50V, C0G, 5%	0603	Std	Std
3	C2, C7, C10	10µF	Capacitor, Ceramic, 10V, X5R, 10%,	0805	GRM21BR61A106KE19L	muRata
2	C3, C4	2.2µF	Capacitor, Ceramic, 16V, X5R, 10%,	0603	GRM188R61C225KE15D	muRata
1	C5	0.1µF	Capacitor, Ceramic, 50V, X7R, 10%,	0805	GRM21BR71H104KA01L	muRata
1	C6	0.1µF	Capacitor, Ceramic, 25V, X7R, 10%,	0603	GRM188R71E104KA01D	muRata
1	C9	10µF	Capacitor, Ceramic, 10V, X5R, 10%,	0805	GRM21BR61A106KE19L	muRata
4	J1, J3, J4, J5	PEC04SAAN	Header, Male 4-pin, 100mil spacing	0.100 inch x 4	PEC04SAAN	Sullins
2	J2, J6	PEC02SAAN	Header, Male 2-pin, 100mil spacing	0.100 inch x 2	PEC02SAAN	Sullins
9	JP1 - JP9	PEC03SAAN	Header, Male 3-pin, 100mil spacing	0.100 inch x 3	PEC03SAAN	Sullins
1	L1	2.2µH	Inductor, SMT, 2.0A, 110milliohm	0.118 x 0.118 inch	LPS3015-222ML	Coilcraft
0	R1, R3, R10, R12	open	Resistor, Chip, 1/16W, 1%	0603	Std	Std
4	R2, R4, R9, R11	0	Resistor, Chip, 1/16W, 1%	0603	Std	Std
3	R5, R6, R15	47.5k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R7, R13, R14	475k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R8	232K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	S1	KT11P2JM	Switch, SPST, PB Momentary, Sealed Tactile	0.245 X 0.251 inch	KT11P2JM	C & K
1	U1	TPS650061RUK	IC, 2.25 MHz Step Down Converter with Dual LDOs and SVS	QFN	TPS650061RUK	TI
9	--		Shunt, 100-mil, Black	0.100	929950-00	3M
1	--		PCB, 2.0" x 2.4" x 0.062"		HPA584	Any
1	--		Label	1.25 x 0.25 inch	THT-13-457-10	Brady

- Notes:
- These assemblies are ESD sensitive, ESD precautions shall be observed.
 - These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
 - These assemblies must comply with workmanship standards IPC-A-610 Class 2.
 - Ref designators marked with an asterisk (***) cannot be substituted. All other components can be substituted with equivalent MFG's components.

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